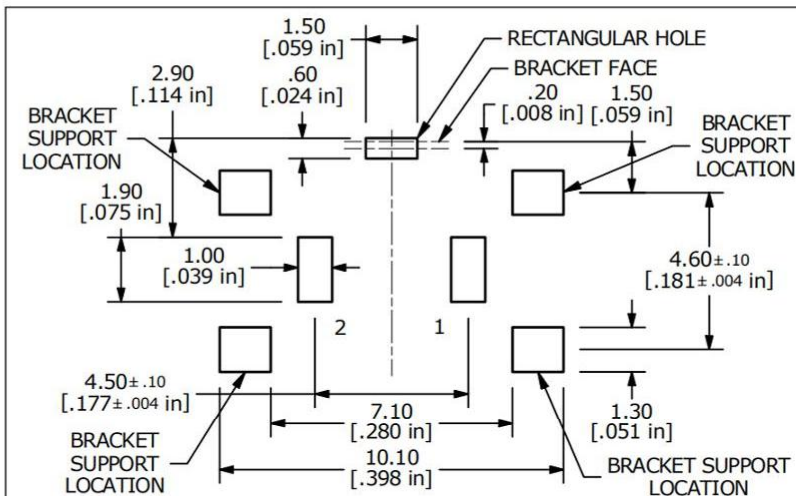
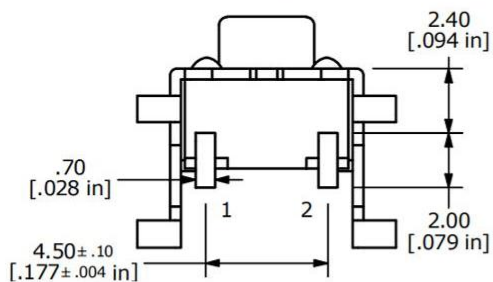
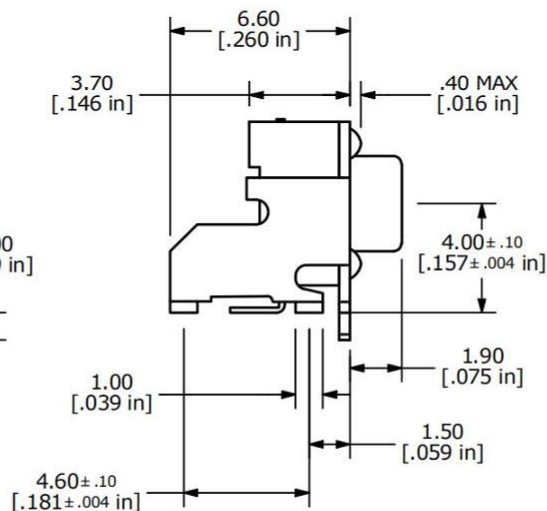
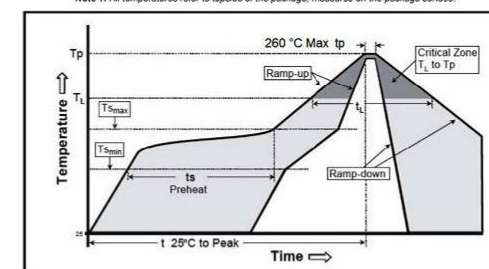


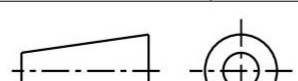
SCHEMATIC



RECOMMENDED PCB LAYOUT

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T_{Sn63} to T_{Pb})	3 °C/second max.	3 °C/second max.
Preheat		
-Temperature Min (T_{Snmin})	100 °C	150 °C
-Temperature Max (T_{Snmax})	150 °C	200 °C
-Time (T_{Snmin} to T_{Snmax})	60-120 seconds	60-180 seconds
-Time Maintained above:		
-Temperature (T_{I})	183 °C	217 °C
-Time (T_{I})	60-150 seconds	60-150 seconds
-Time within 5 °C of actual Peak Temperature (t_{p})	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.



TITLE	TACT SWITCH			DRAWN	许金龙	TOLERANCE OTHERWISE UNLESS SPECIFIED					
PRODUCT NO.	XB-TS-3316			CHECKED	吴永友						
DRAWING NO.				APPROVED	赵崇生	TOLERANCE	± 0.2				
SCALE	5:1	UNIT	mm	DATE		ANGLE TOL	± 1°				
 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.											
								NO.	PARTS	MATERIAL	QTY